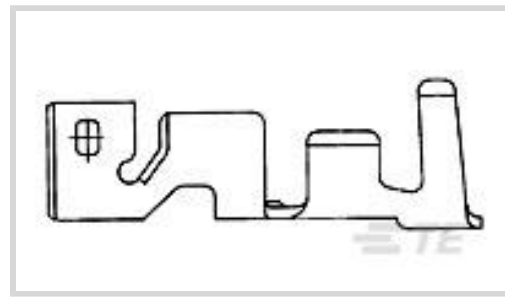




Connectors > PCB Connectors > Wire-to-Board Connectors > Wire-to-Board Connector Contacts



Contact Type: **Socket**

Wire Size: **.05 – .35 mm²**

Contact Mating Area Plating Material: **Tin**

Packaging Method: **Strip**

Features

Product Type Features

| | |
|-----------------------------------|--------------|
| Sealable | No |
| Connector & Contact Terminates To | Wire & Cable |

Configuration Features

| | |
|-----------------------------------|---------------|
| Compatible With Wire & Cable Type | Discrete Wire |
|-----------------------------------|---------------|

Electrical Characteristics

| | |
|-----------------------|---------|
| Insulation Resistance | 1000 MΩ |
|-----------------------|---------|

Contact Features

| | |
|---|-----------------|
| Mating Pin Diameter | .64 mm[.025 in] |
| Wire Contact Termination Area Plating Thickness | .8 μm |
| Wire Contact Termination Area Plating Material | Pre-Tin |
| Contact Mating Area Plating Material Thickness | .8 μm |
| Contact Base Material | Phosphor Bronze |
| Contact Type | Socket |
| Contact Mating Area Plating Material | Tin |
| Contact Current Rating (Max) | 2 A, 2.5 A |

Termination Features

| | |
|------------------------------------|-------|
| Termination Method to Wire & Cable | Crimp |
|------------------------------------|-------|

Mechanical Attachment

| | |
|-------------------------|------|
| Wire Insulation Support | With |
|-------------------------|------|

Dimensions

| | |
|--|-----------------------------|
| Accepts Wire Insulation Diameter Range | 1 – 1.9 mm [.039 – .075 in] |
| Wire Size | .05 – .35 mm ² |

Usage Conditions

| | |
|-----------------------------|-----------------------------|
| Operating Temperature Range | -25 – 105 °C [-13 – 221 °F] |
|-----------------------------|-----------------------------|

Operation/Application

| | |
|---------------------|--------|
| Circuit Application | Signal |
|---------------------|--------|

Packaging Features

| | |
|--------------------|-------|
| Packaging Quantity | 10000 |
| Packaging Method | Strip |

Product Compliance

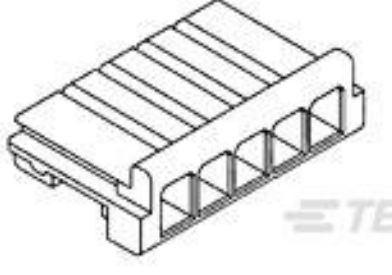
[For compliance documentation, visit the product page on TE.com>](#)

| | |
|---|--|
| EU RoHS Directive 2011/65/EU | Compliant |
| EU ELV Directive 2000/53/EC | Compliant |
| China RoHS 2 Directive MIIT Order No 32, 2016 | No Restricted Materials Above Threshold |
| EU REACH Regulation (EC) No. 1907/2006 | Current ECHA Candidate List: JUNE 2022 (224) Candidate List Declared Against: JAN 2022 (223) SVHC > Threshold: Not Yet Reviewed |
| Halogen Content | Low Halogen - Br, Cl, F, I < 900 ppm per homogenous material. Also BFR/CFR/PVC Free |
| Solder Process Capability | Not applicable for solder process capability |

Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: <https://echa.europa.eu/guidance-documents/guidance-on-reach>

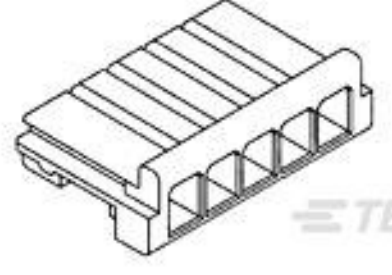
Compatible Parts



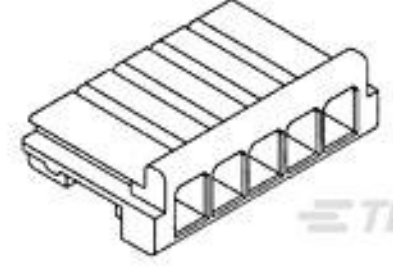
TE Part # 92009-6
RCPT HSG METRIC INTERCONN SYS



TE Part # 92009-3
RCPT HSG METRIC INTERCONN SYS



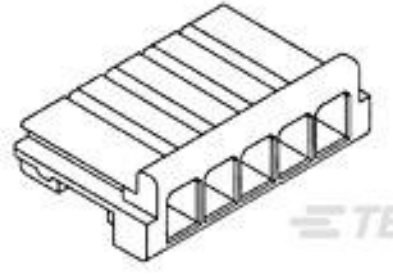
TE Part # 92009-2
RCPT HSG, METRIC INTERCONN SYS



TE Part # 92009-8
RCPT HSG METRIC INTERCONN SYS



TE Part # 1-92009-0
RCPT HSG METRIC INTERCONN SYS



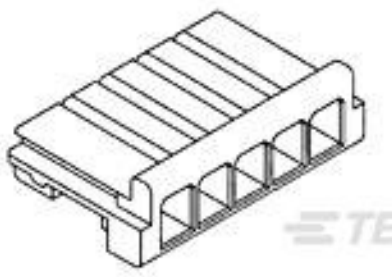
TE Part # 92009-4
RCPT HSG METRIC INTERCONN SYS



TE Part # 1-92009-2
RCPT HSG METRIC INTERCONN SYS



TE Part # 292034-1
CONTACT 2.5 MIS (MATSUSHITA)




TE Part # 92009-7
RCPT HSG METRIC INTERCONN SYS


Also in the Series | MIS



PCB Headers & Receptacles(23)

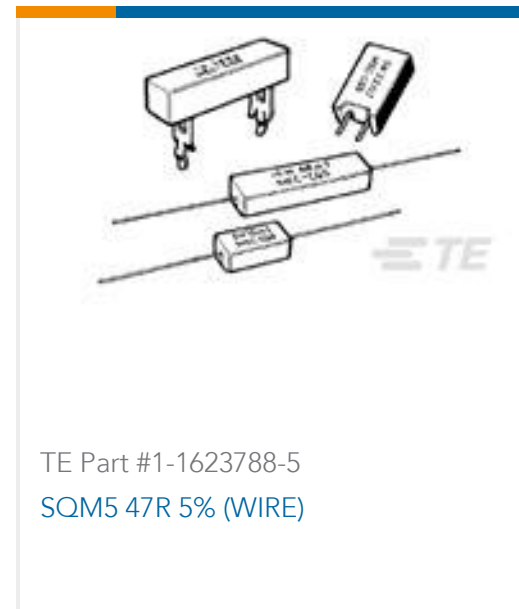


Wire-to-Board Connector Assemblies & Housings(25)



Wire-to-Board Connector Contacts(3)

Customers Also Bought



Documents

Product Drawings

CMPSNP CONT. METINTERCONN SYS.

English

CAD Files

3D PDF

3D

Customer View Model

[ENG_CVM_CVM_92007-1_H_c-92007-1-h.2d_dxf.zip](#)

English

Customer View Model

[ENG_CVM_CVM_92007-1_H_c-92007-1-h.3d_igs.zip](#)

English

Customer View Model

[ENG_CVM_CVM_92007-1_H_c-92007-1-h.3d_stp.zip](#)

English

By downloading the CAD file I accept and agree to the [Terms and Conditions](#) of use.

Product Specifications

Application Specification

English

Application Specification

English

Crimp-Snap Metric Interconnect System

English

Product Environmental Compliance



[MD_92007-1_10262016333_dmtec](#)

English

[MD_92007-1_10262016333_dmtec](#)

English